

FIG. 1

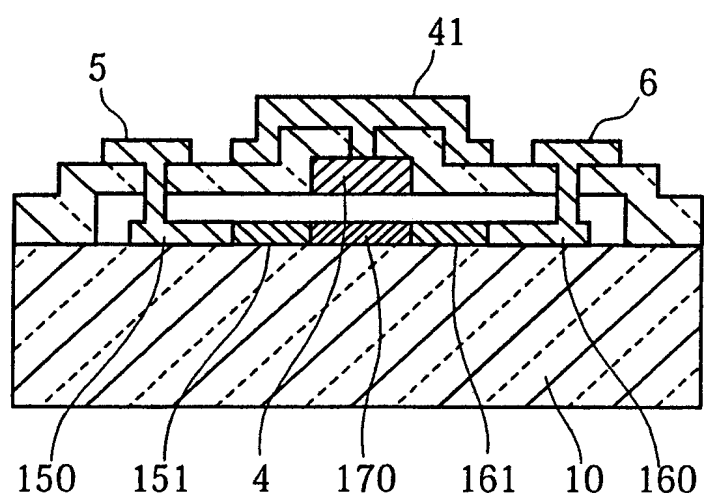


FIG. 2

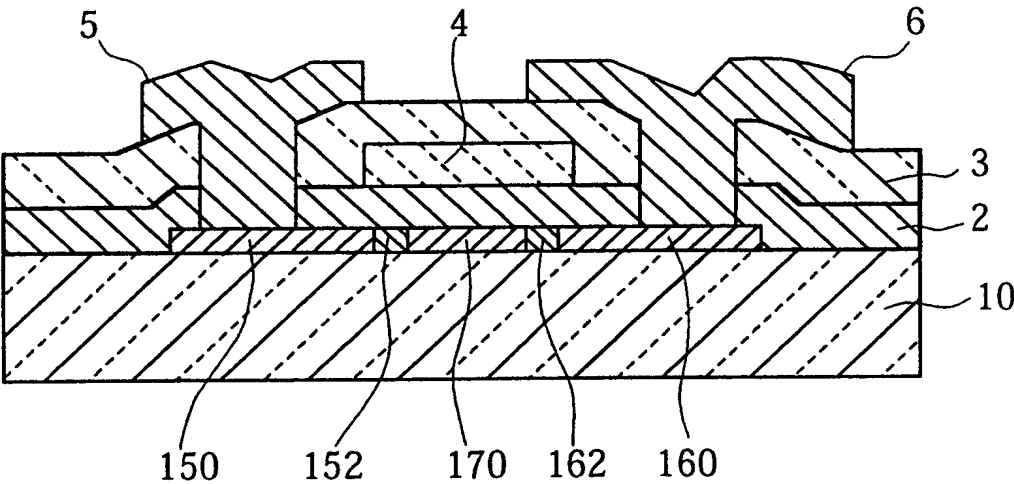


FIG. 3

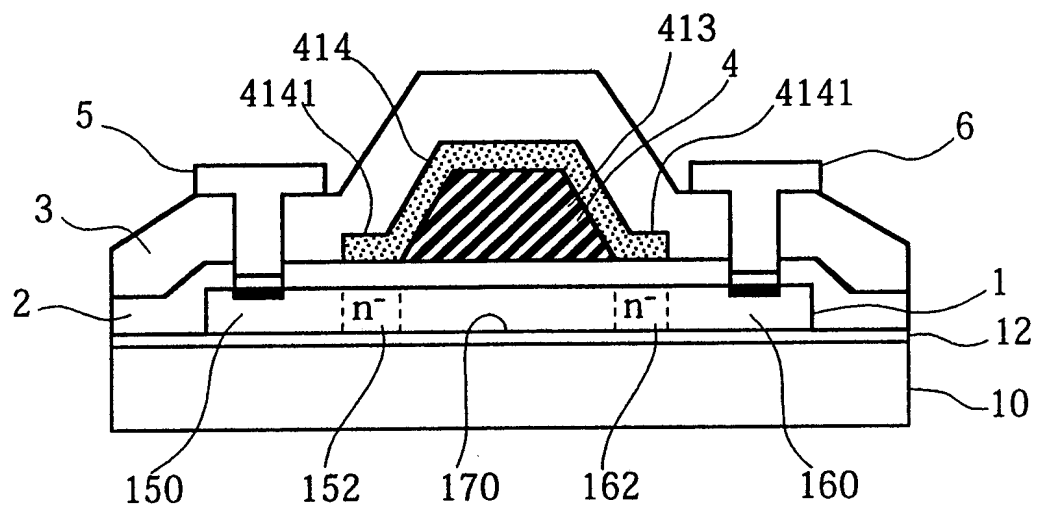


FIG. 4

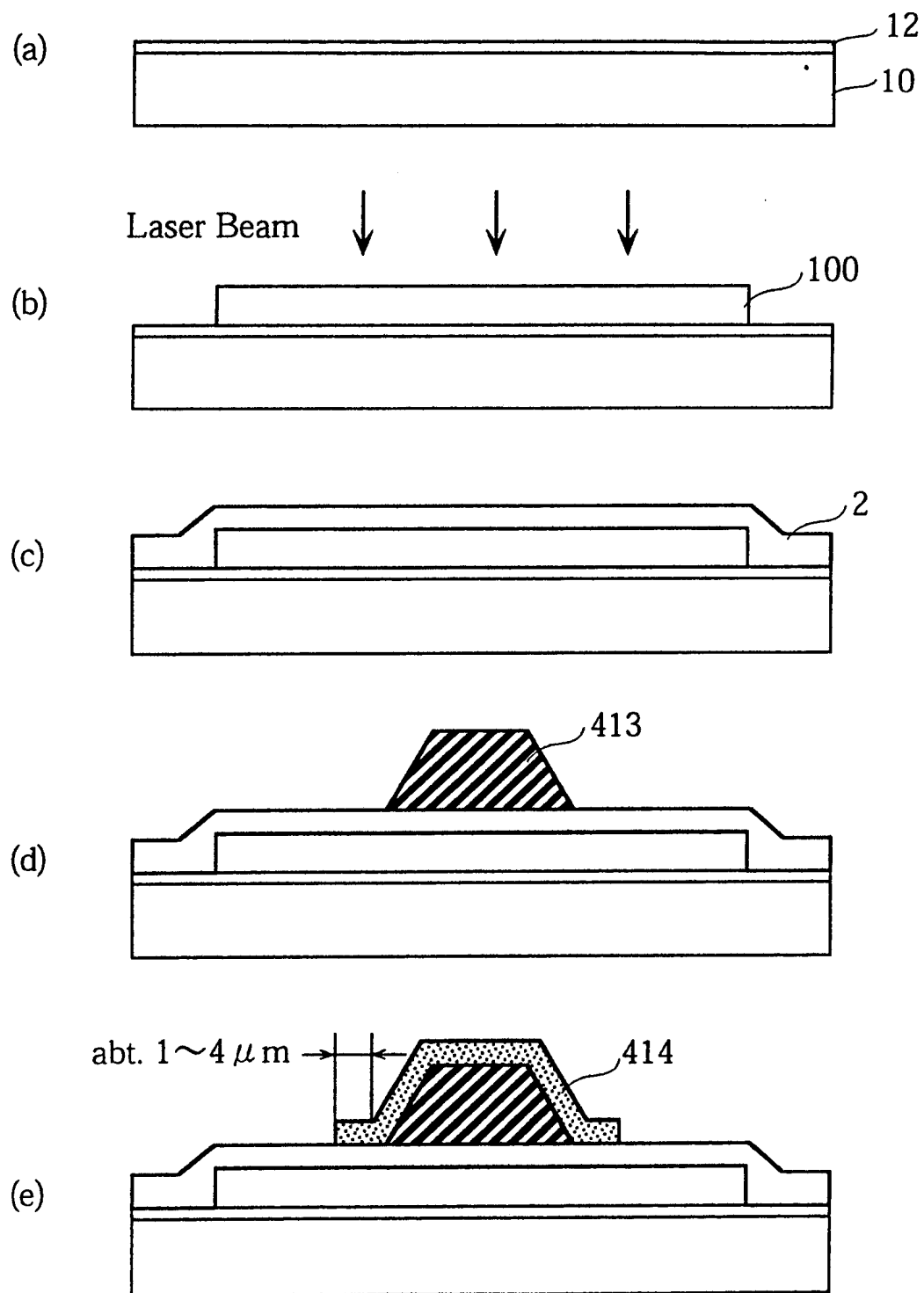


FIG. 5

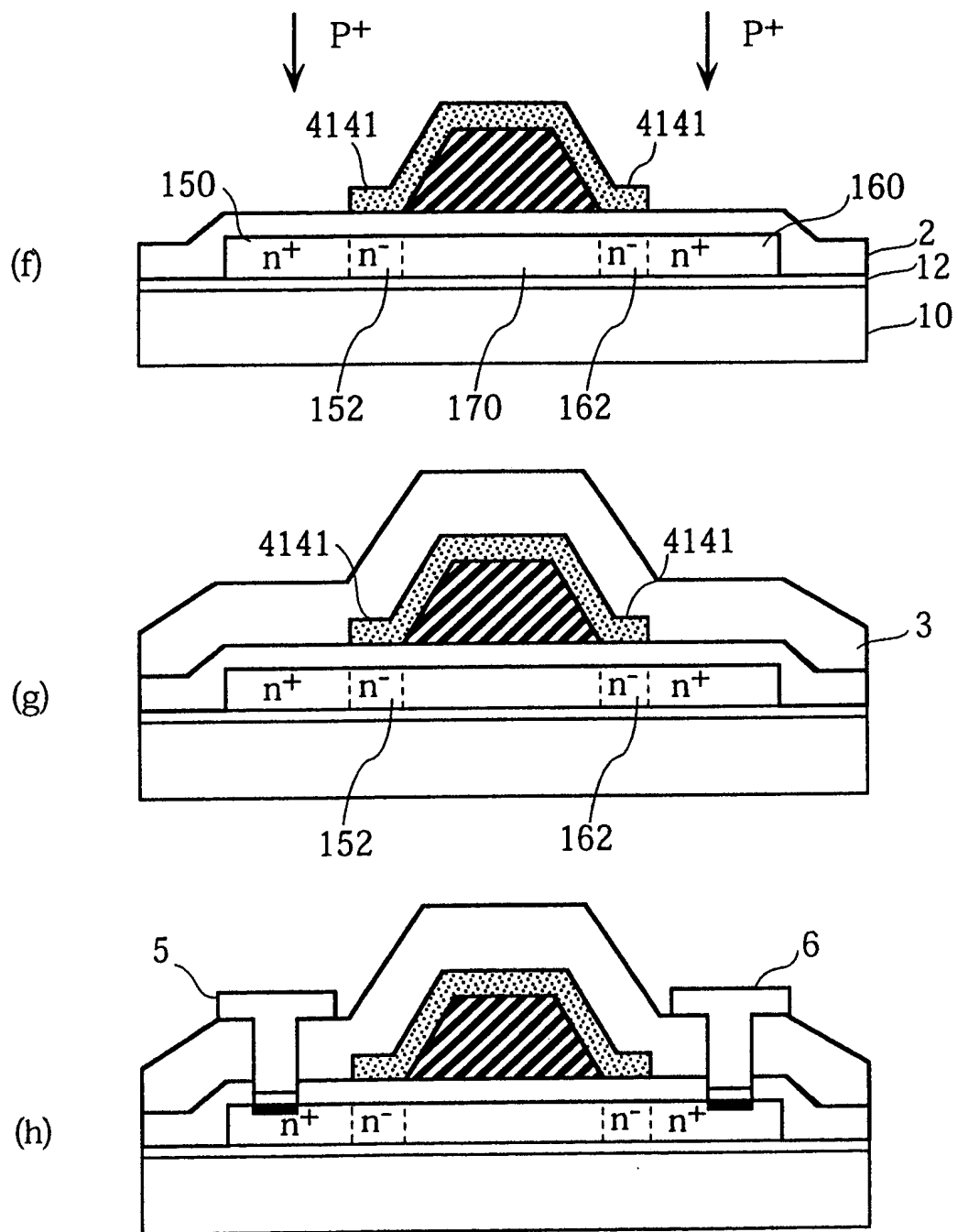


FIG. 6

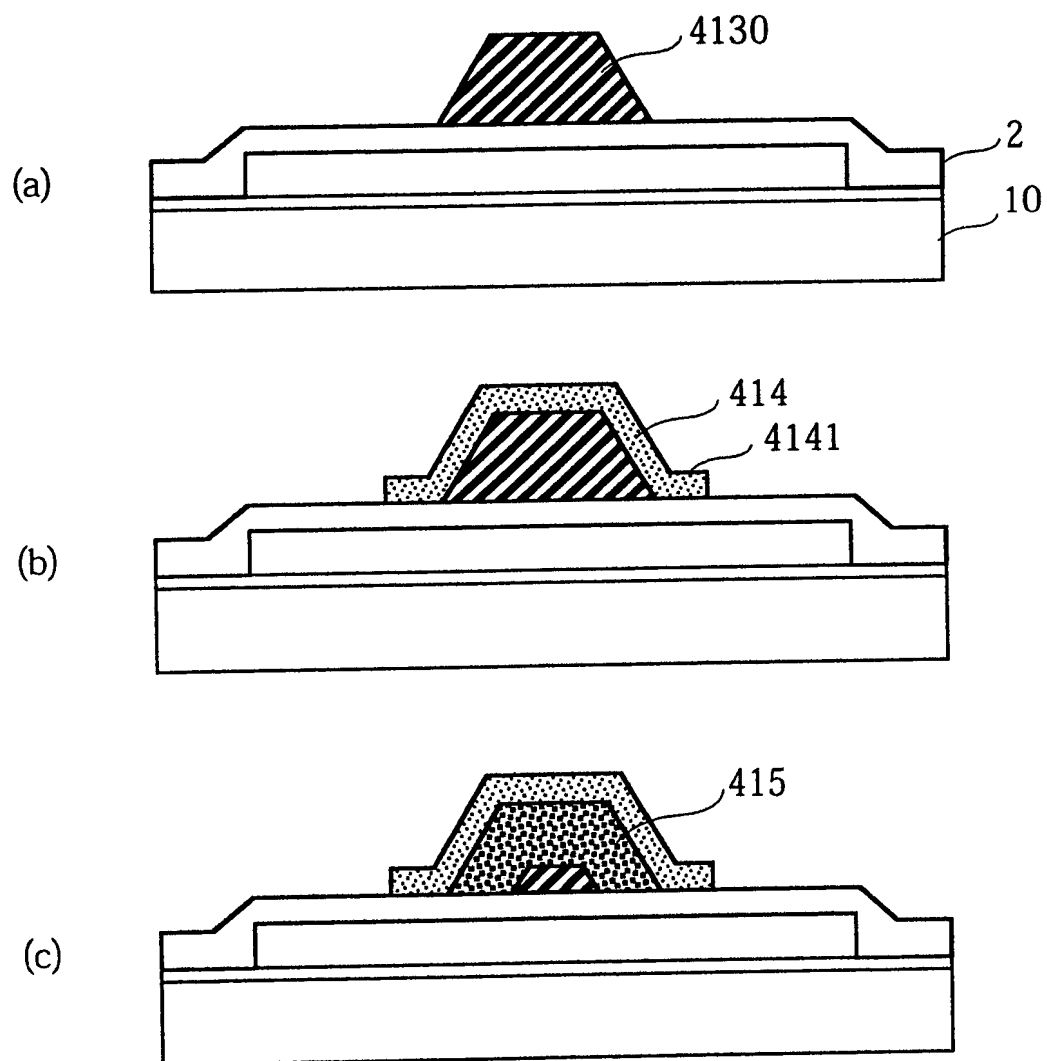


FIG. 7

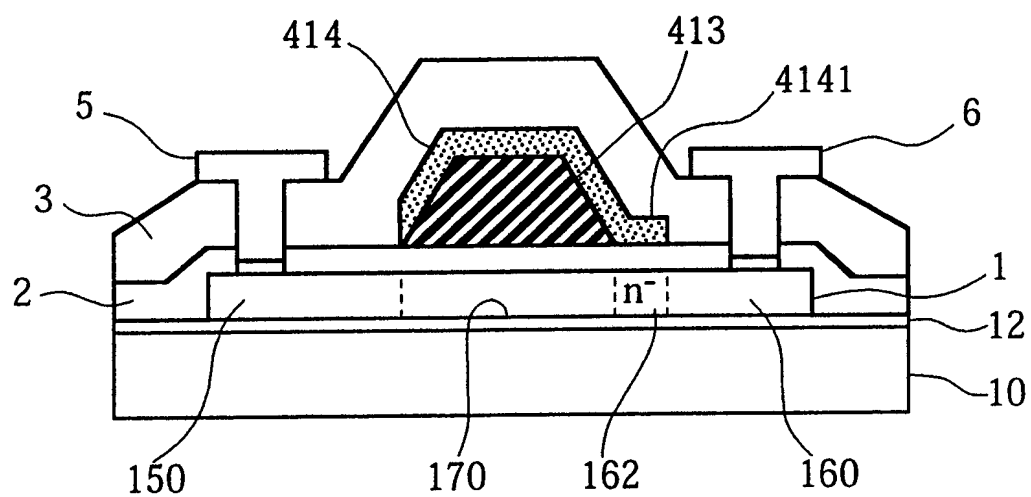


FIG. 8

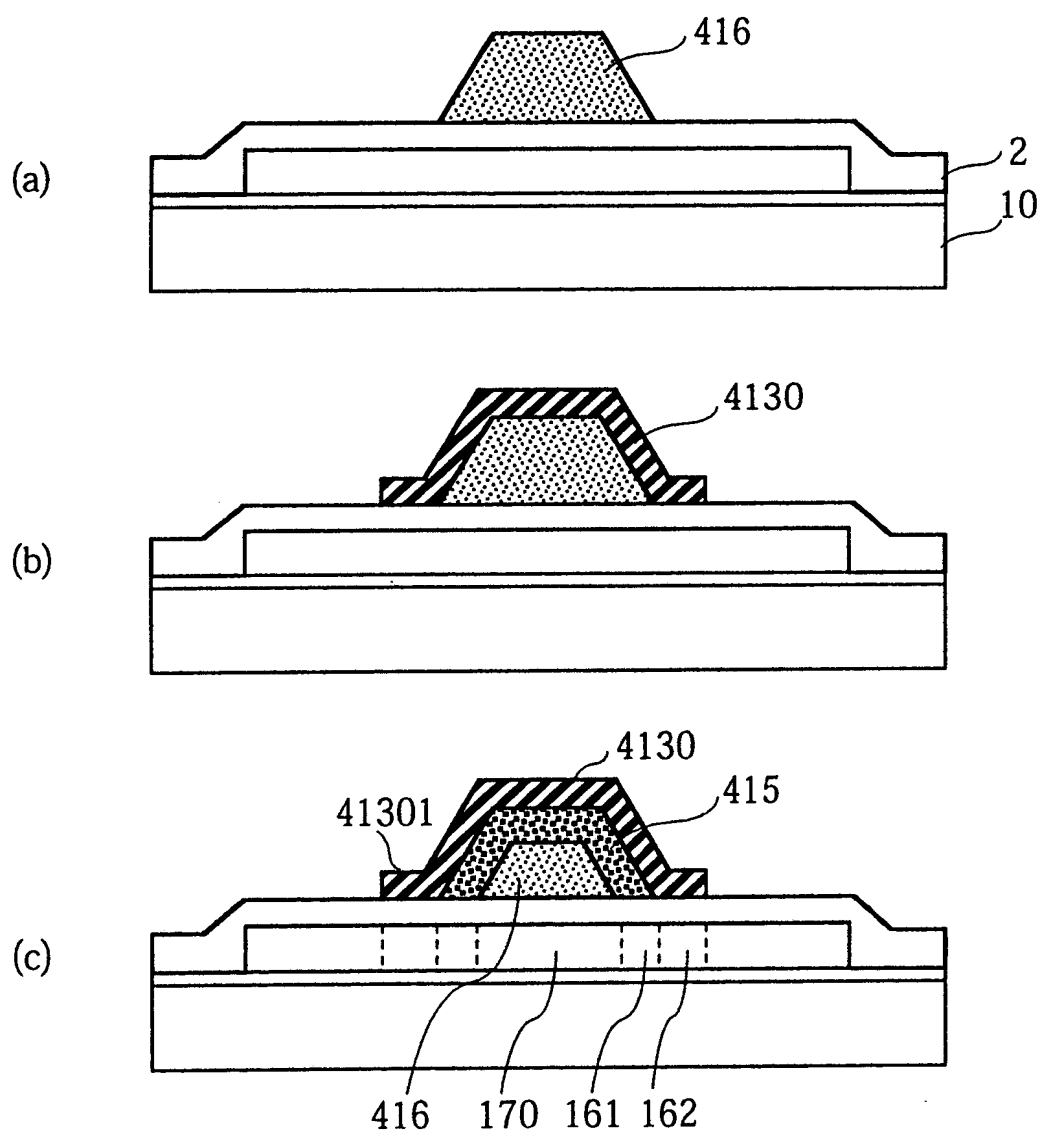


FIG. 9

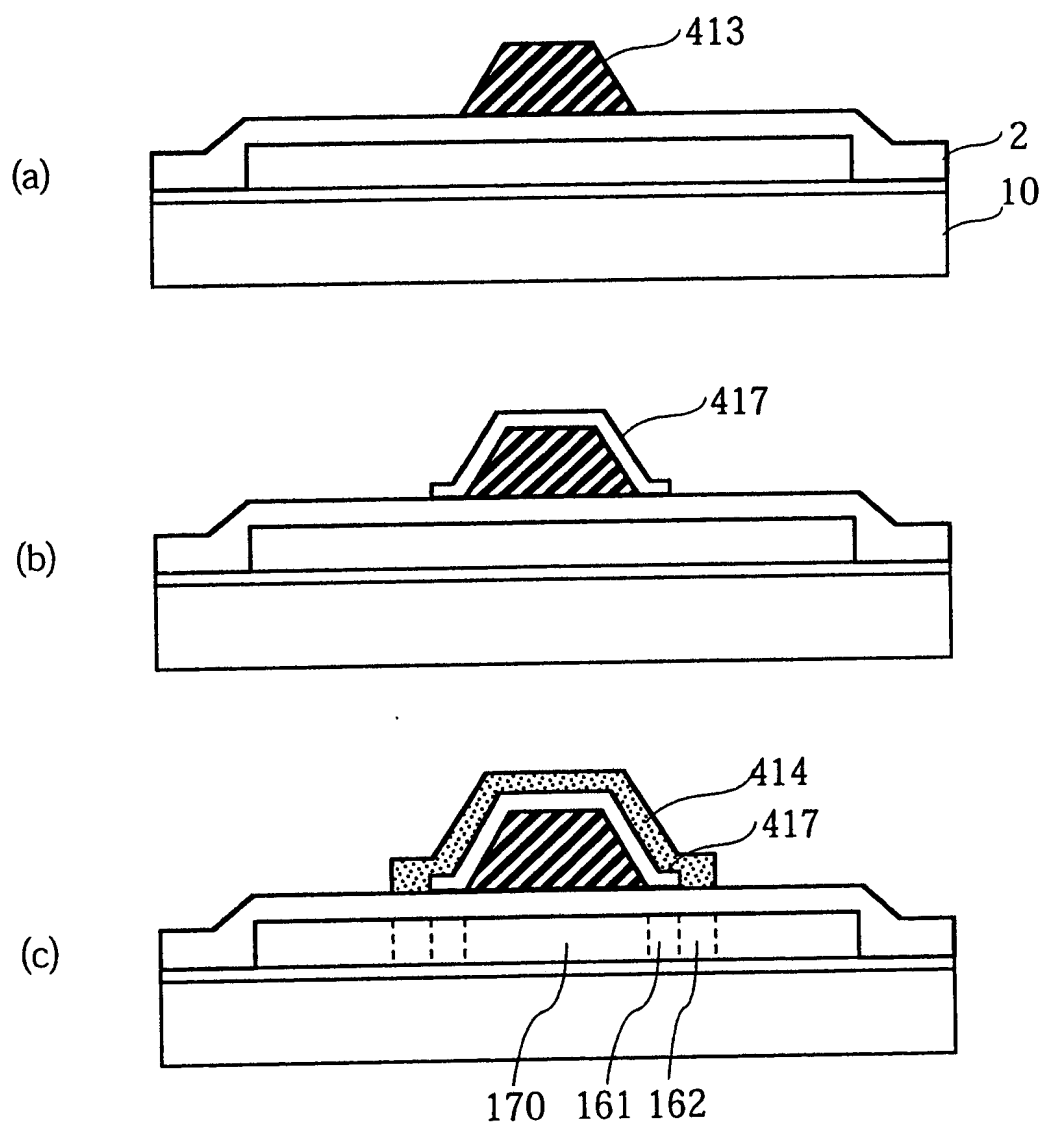


FIG. 10

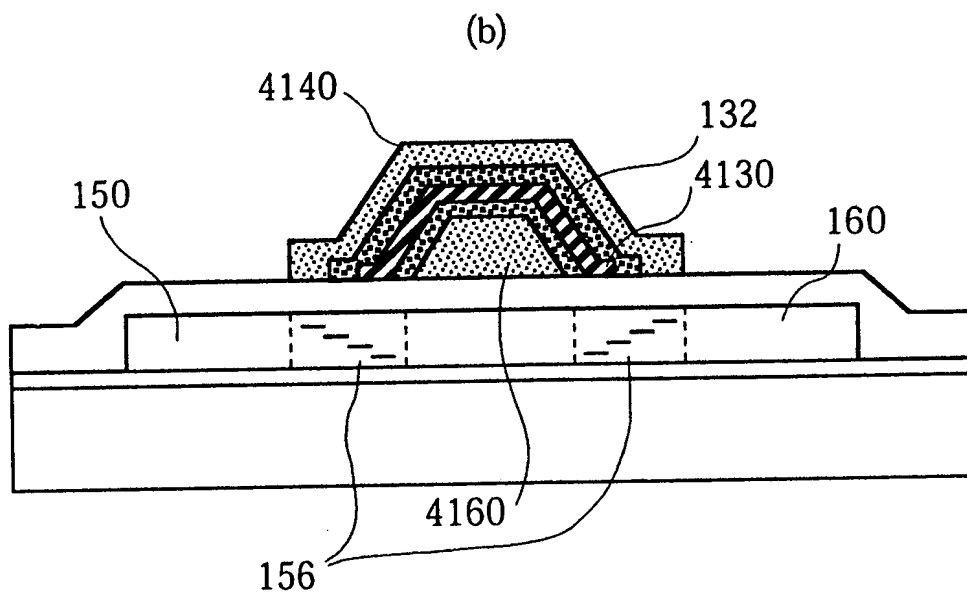
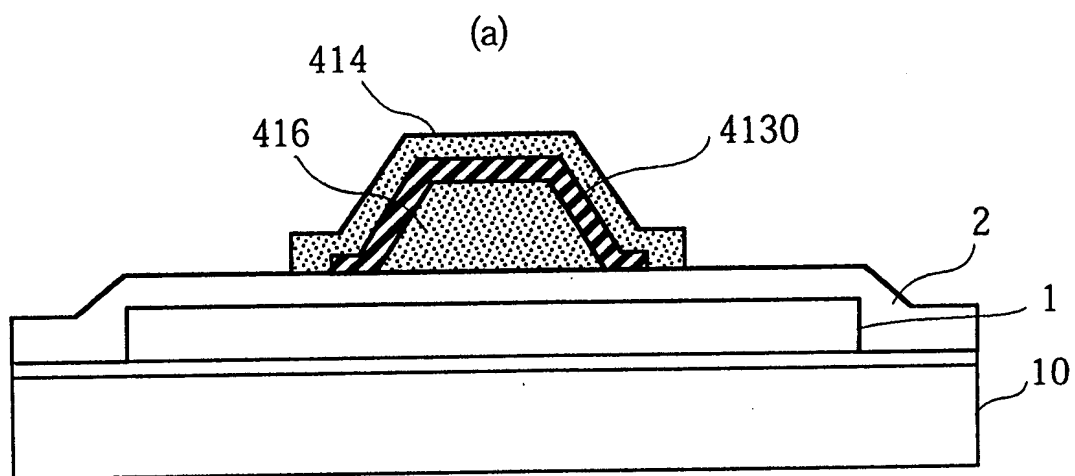


FIG. 11

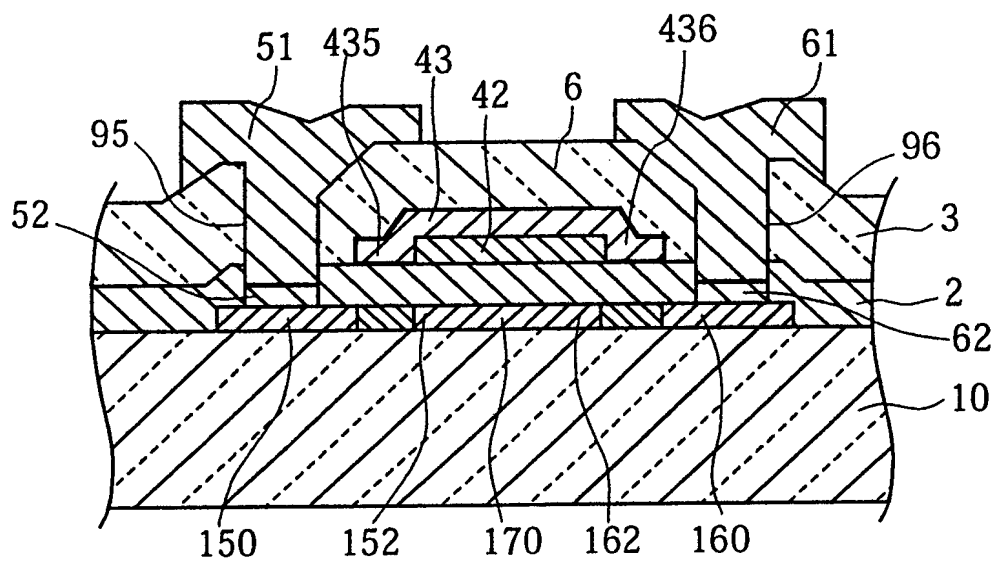


FIG. 12

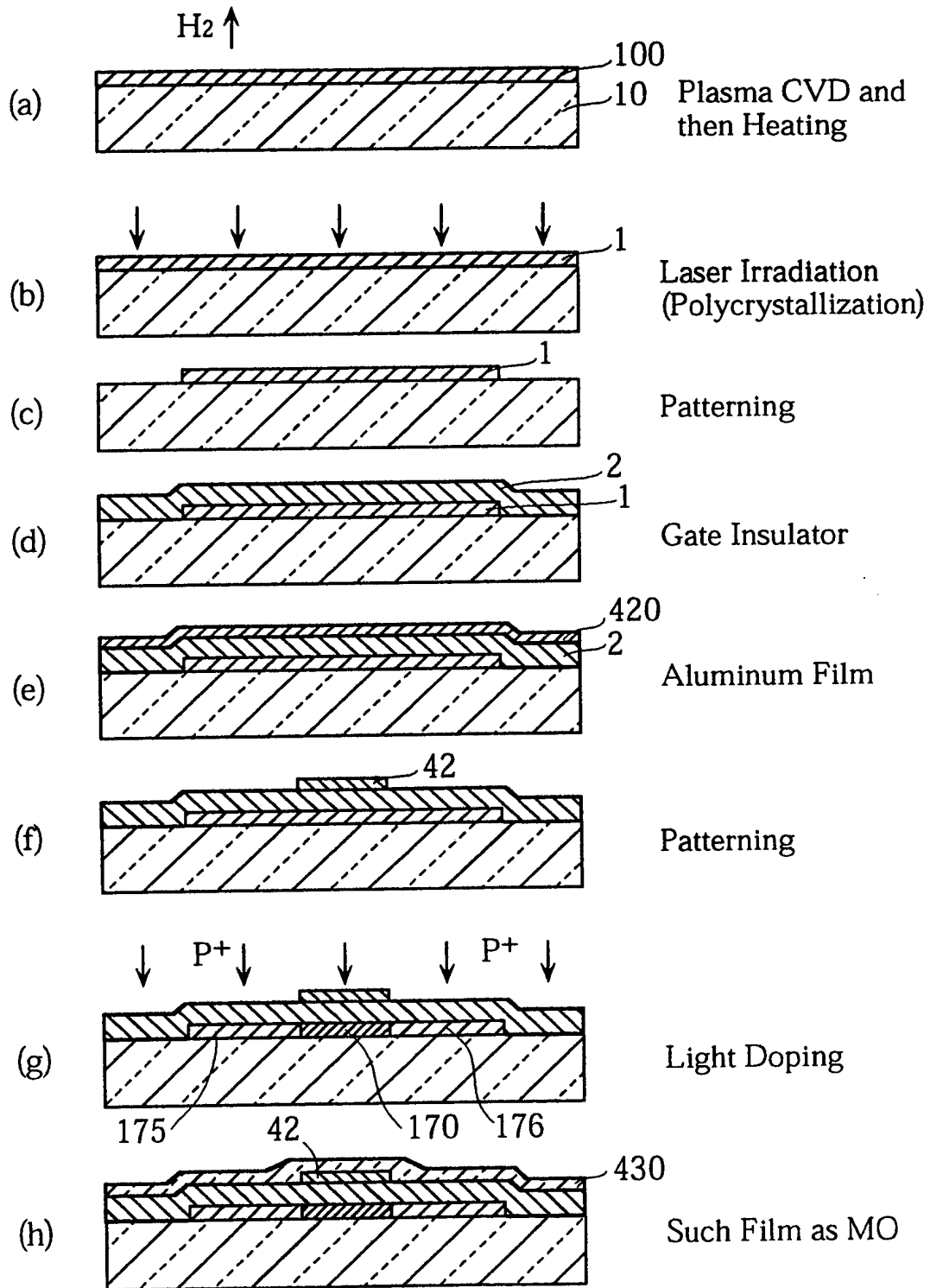


FIG. 13

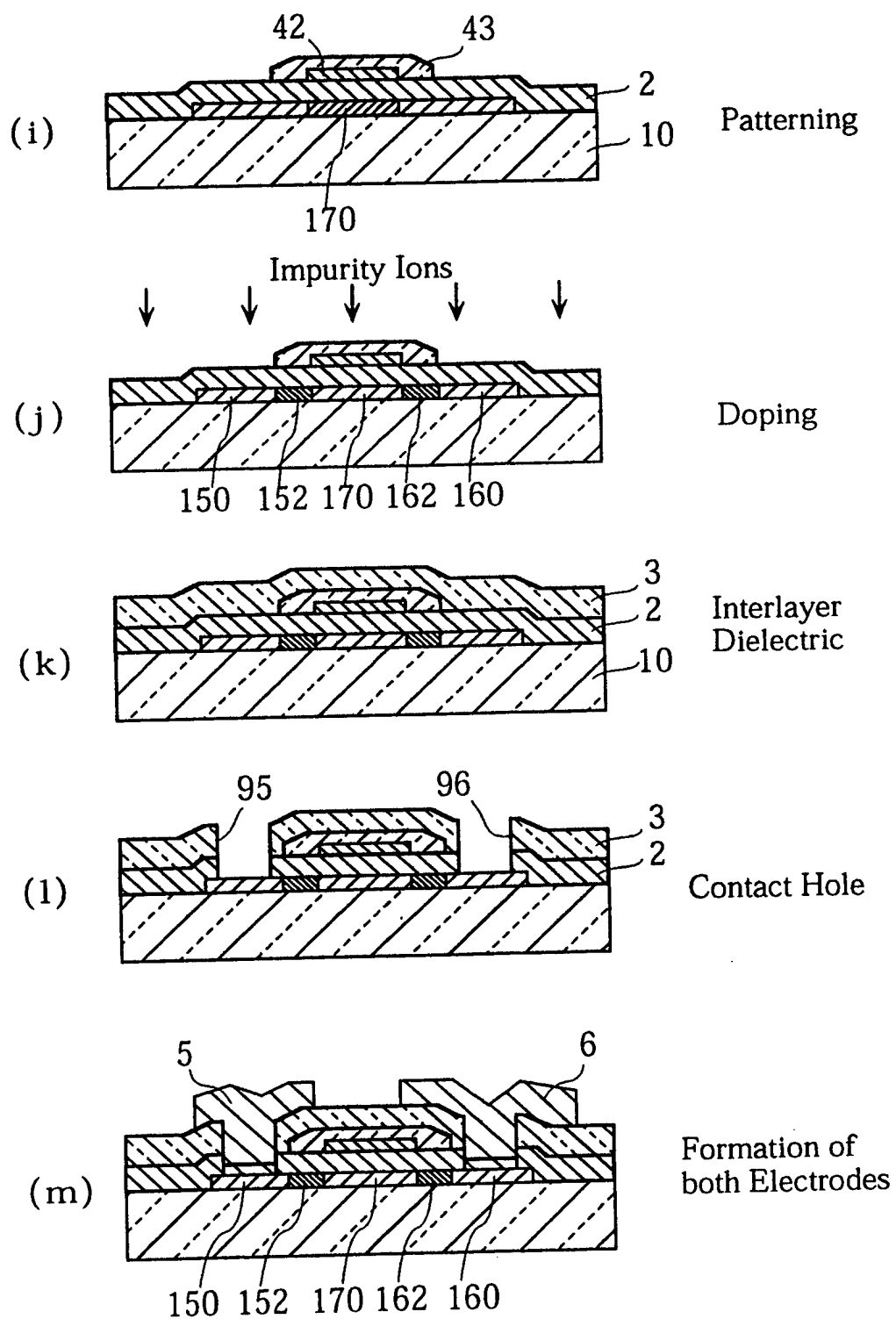


FIG. 14

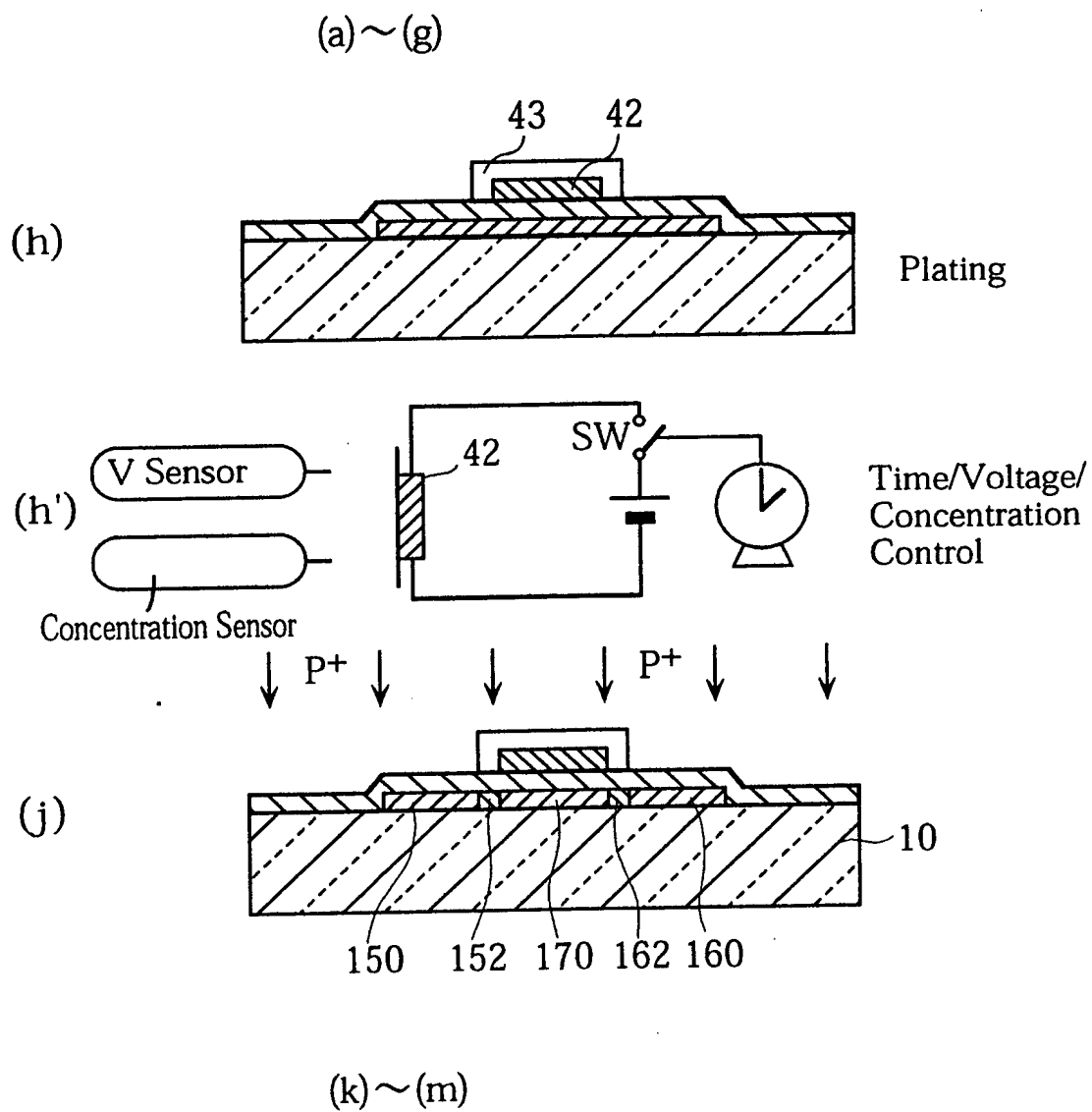


FIG. 15

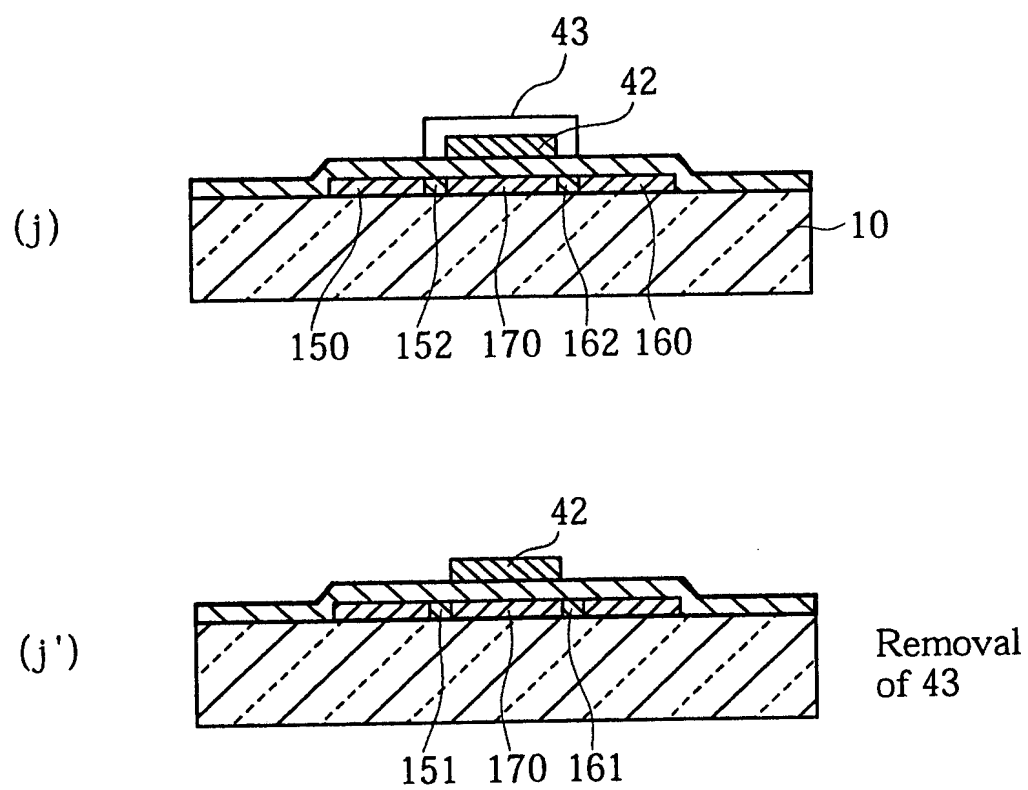


FIG. 16

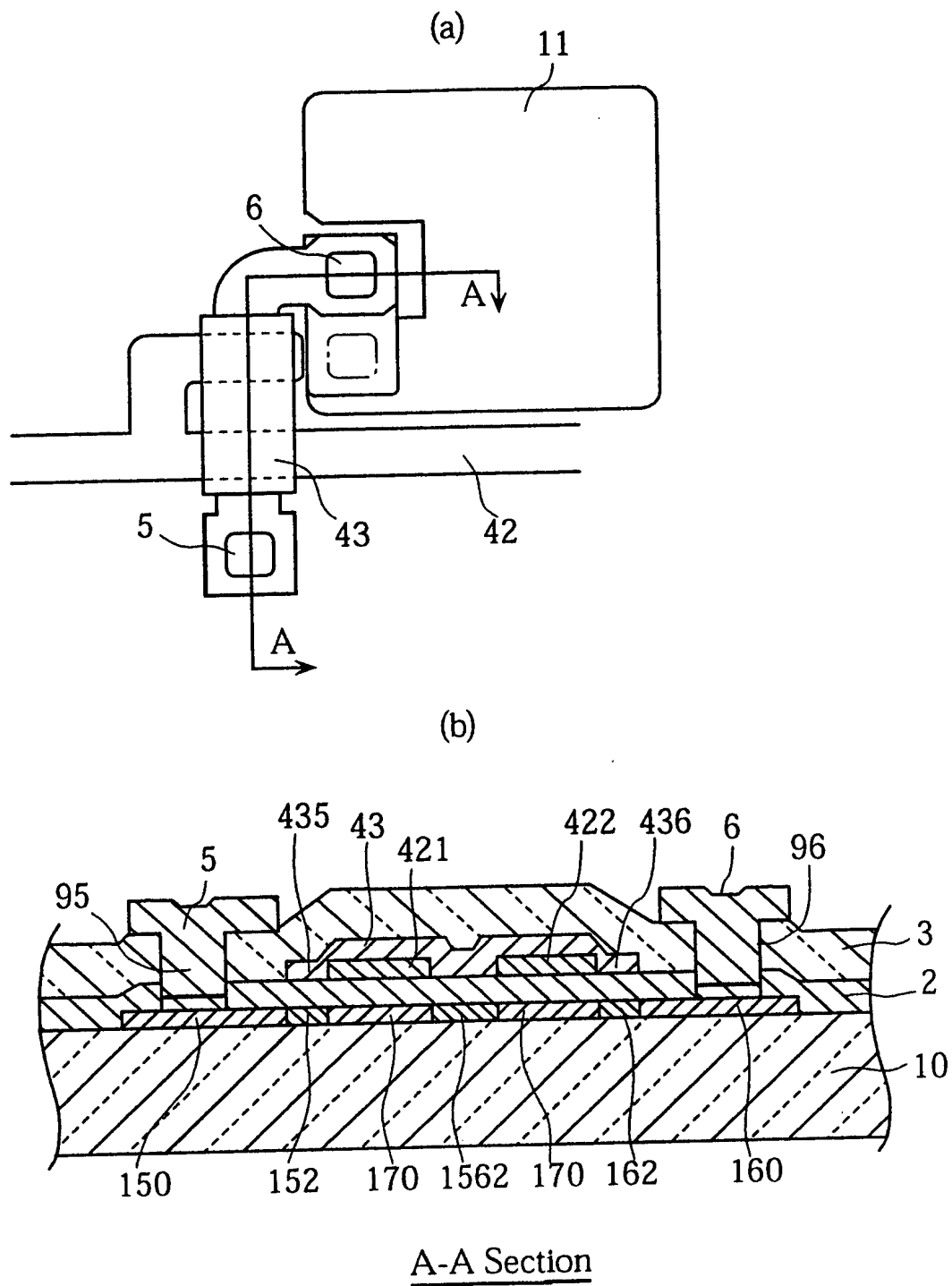
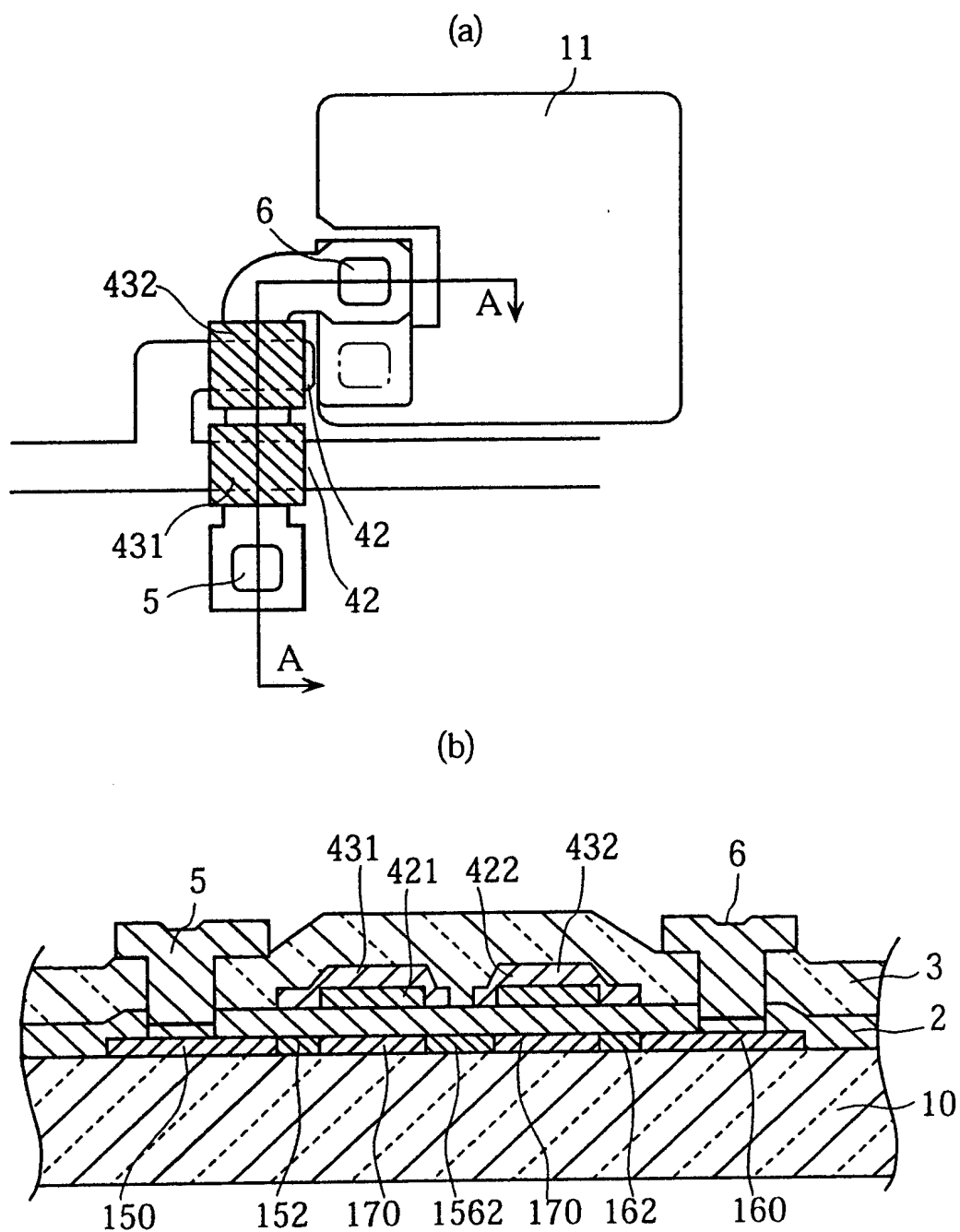


FIG. 17



A-A Section

FIG. 18

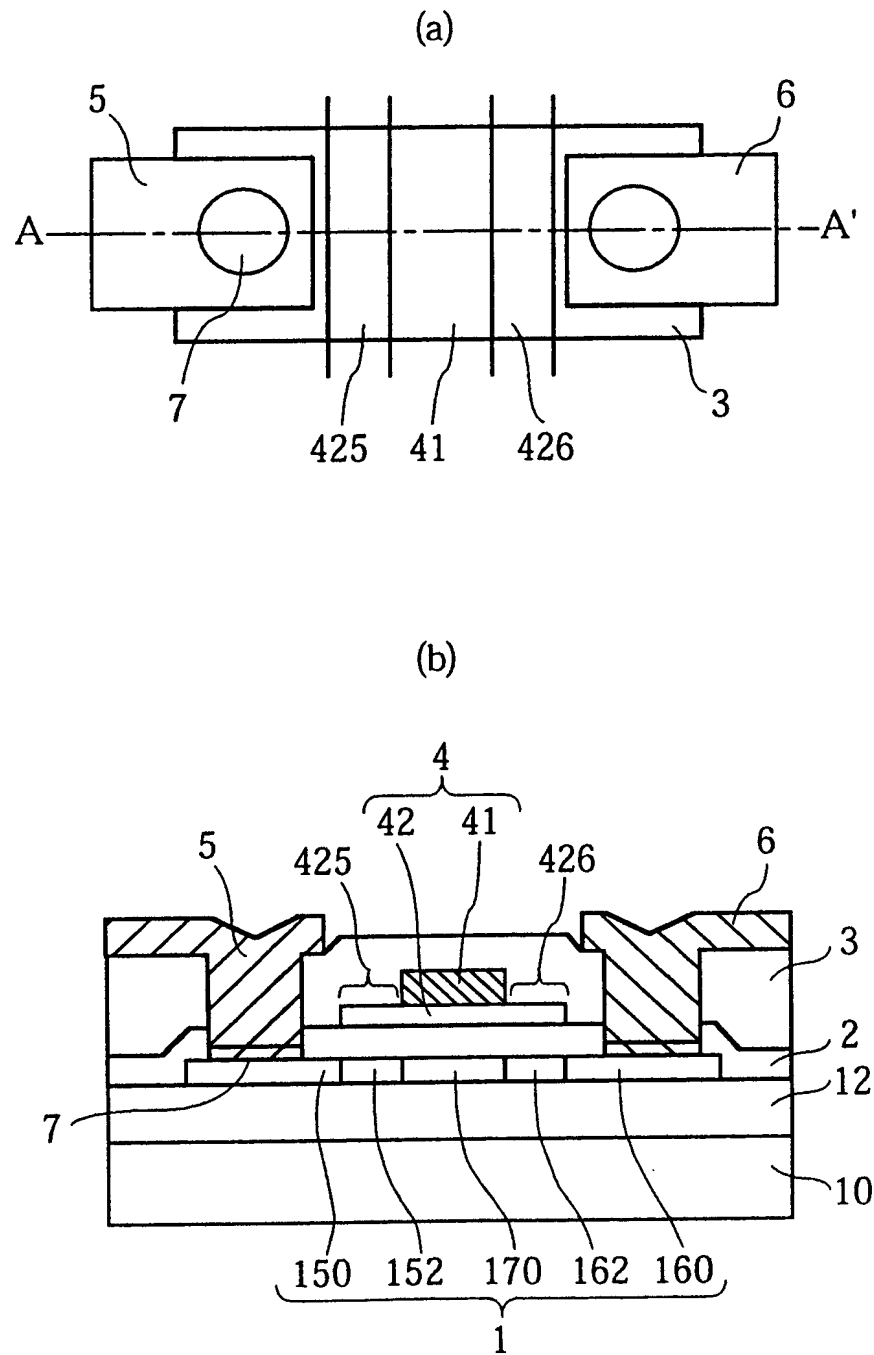


FIG. 19

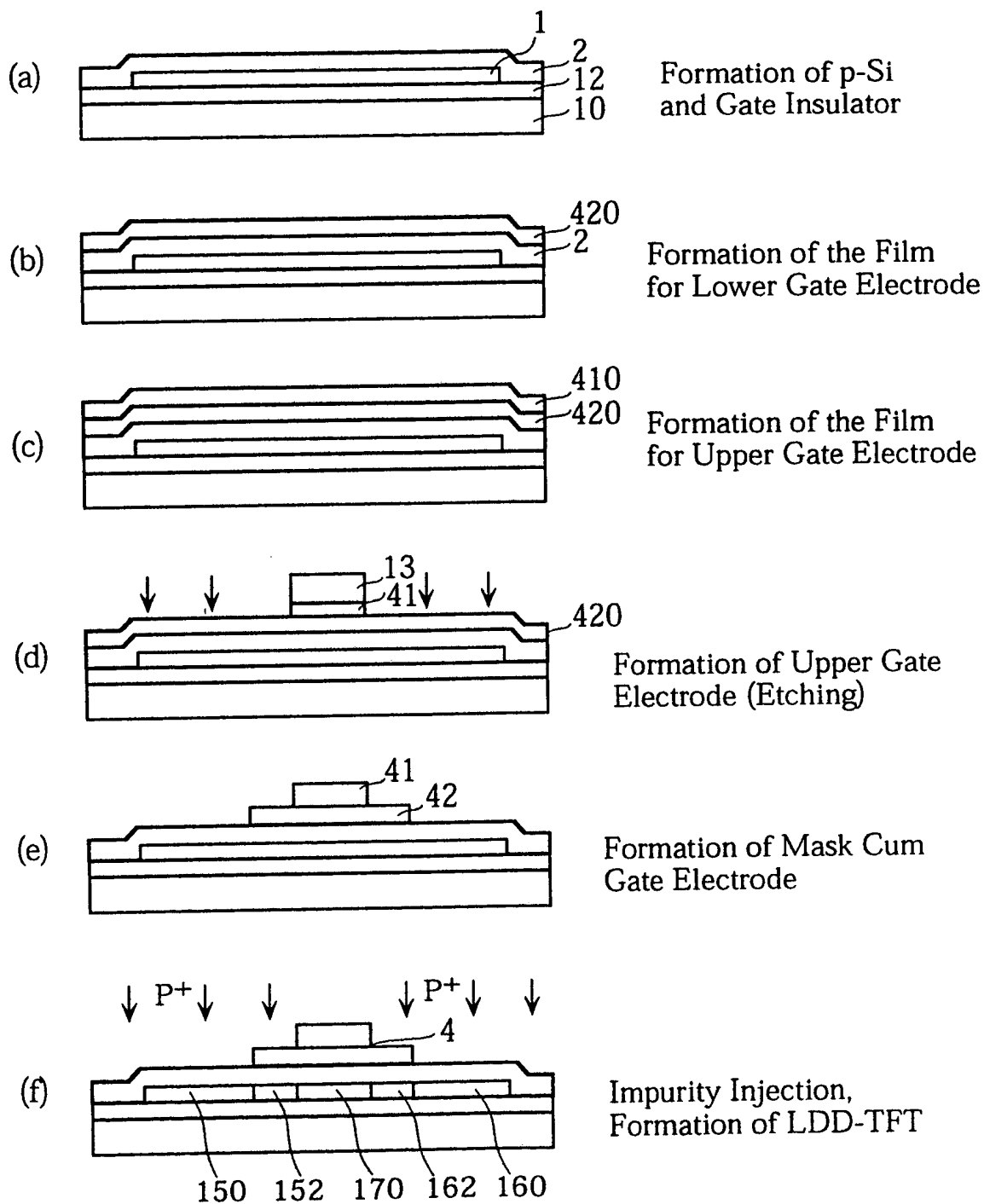


FIG. 20

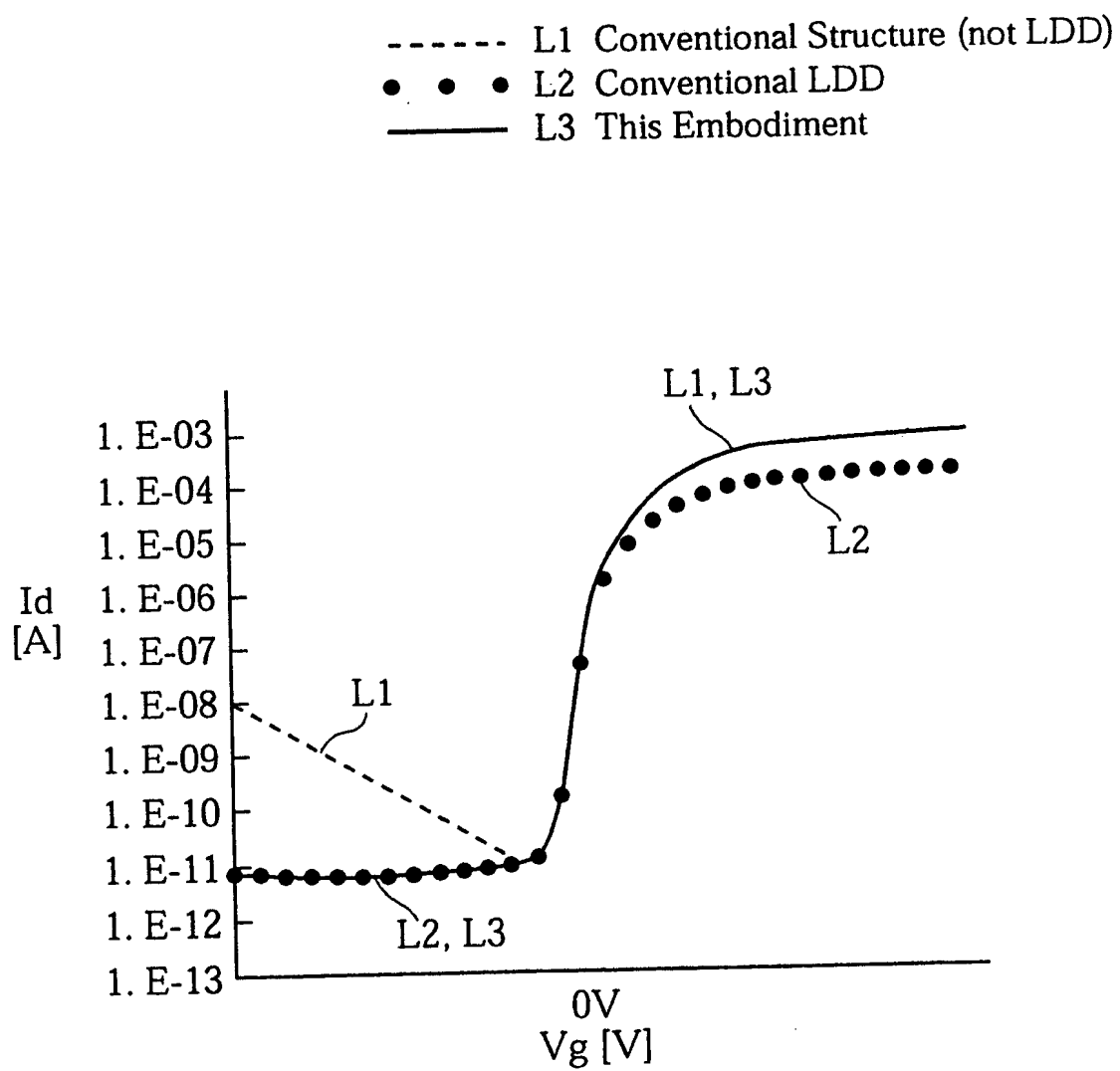


FIG. 21

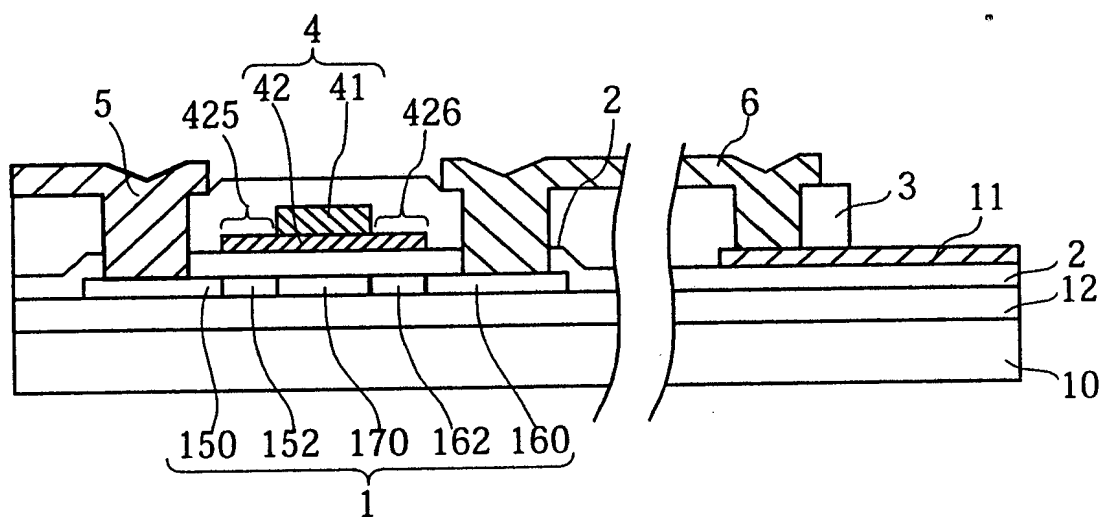


FIG. 22

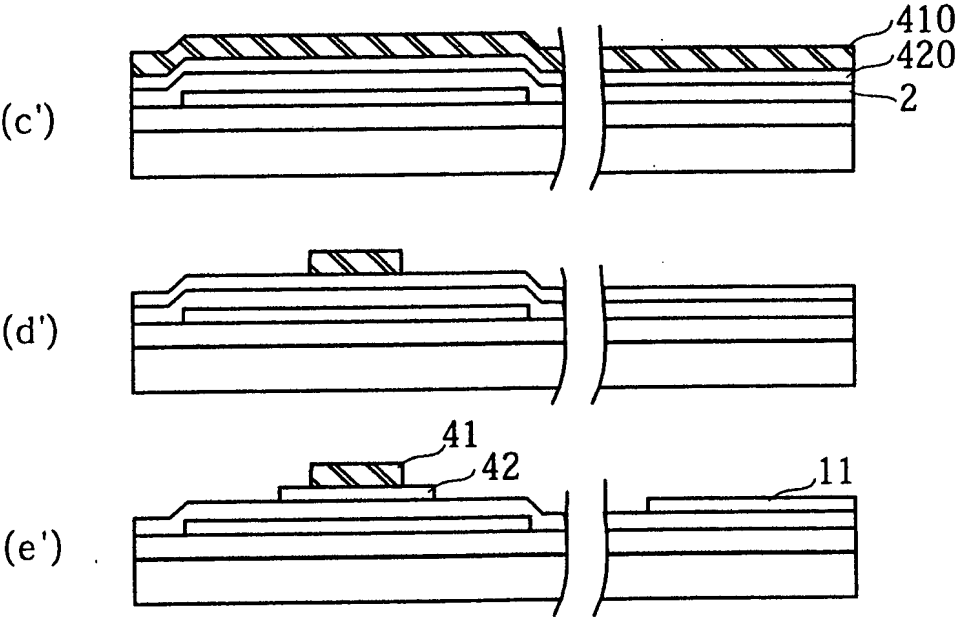


FIG. 23

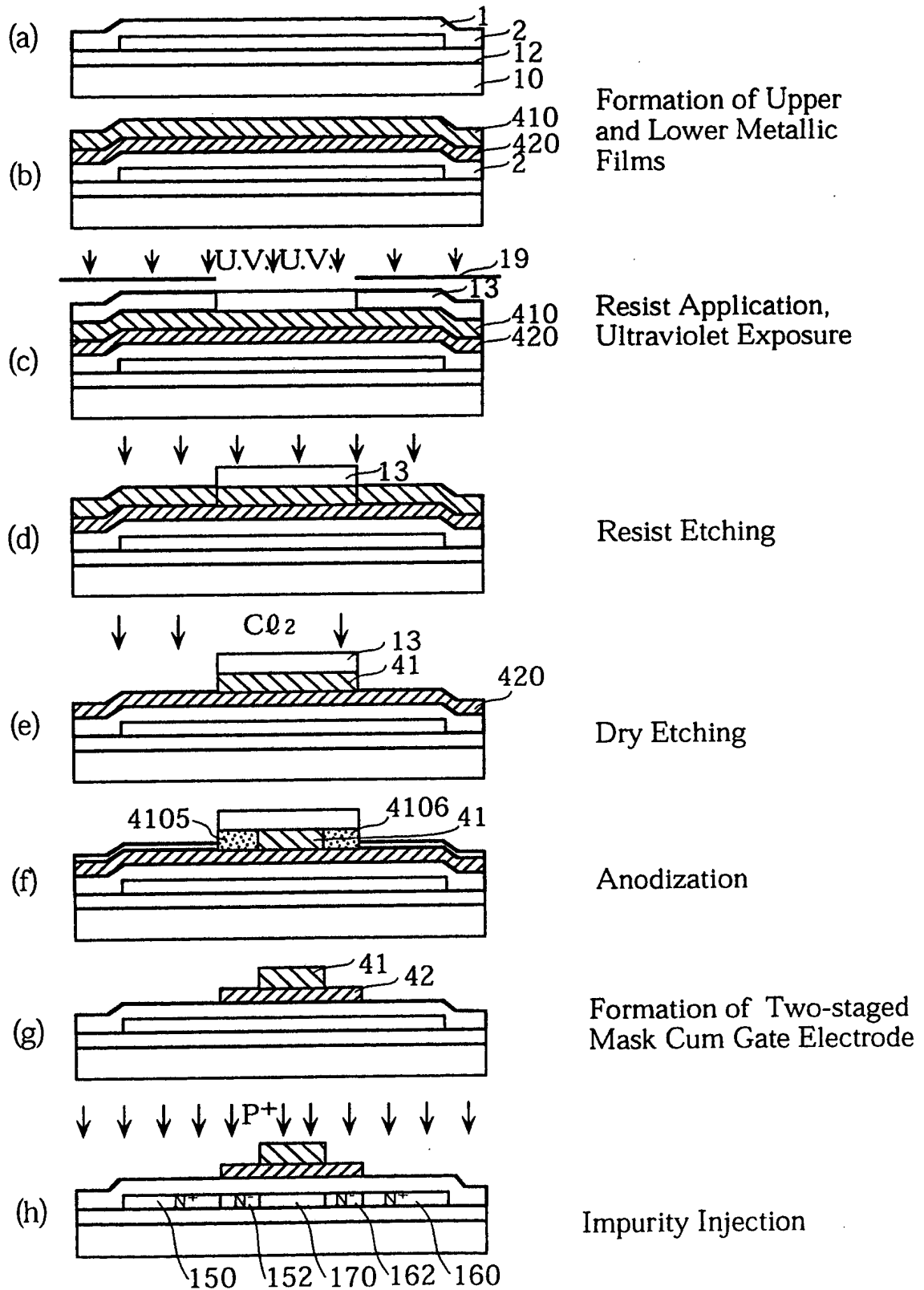


FIG. 24

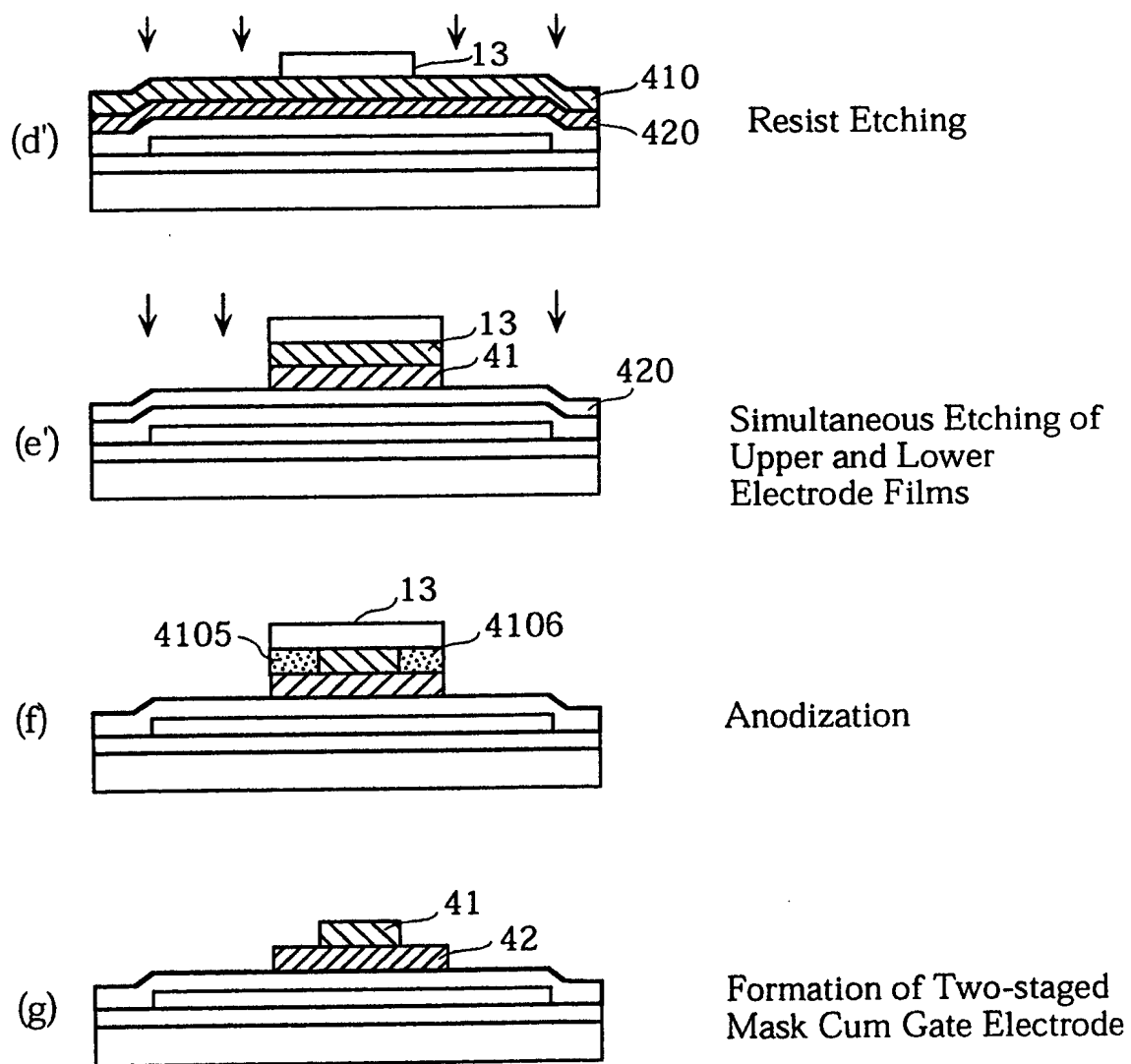


FIG. 25

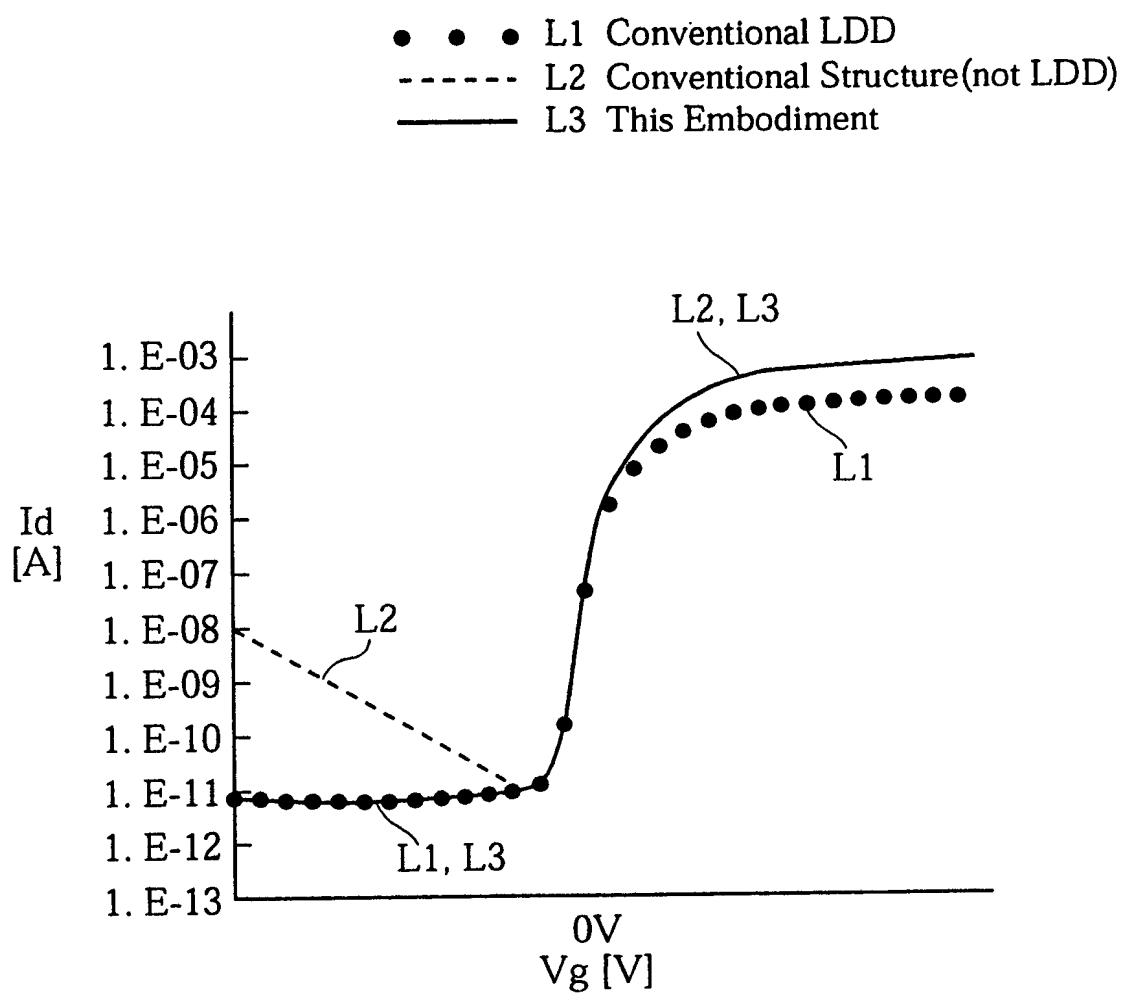


FIG. 26

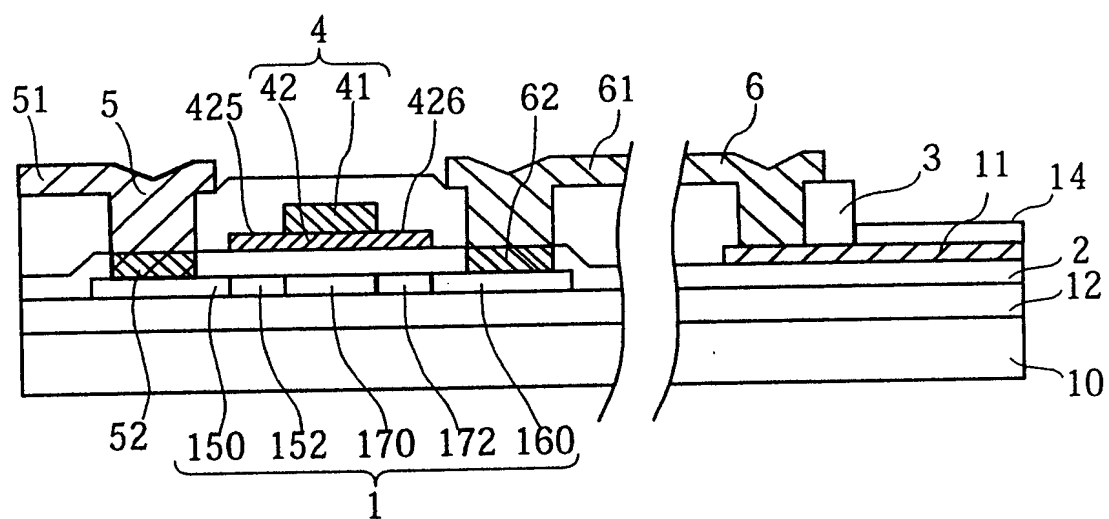


FIG. 27

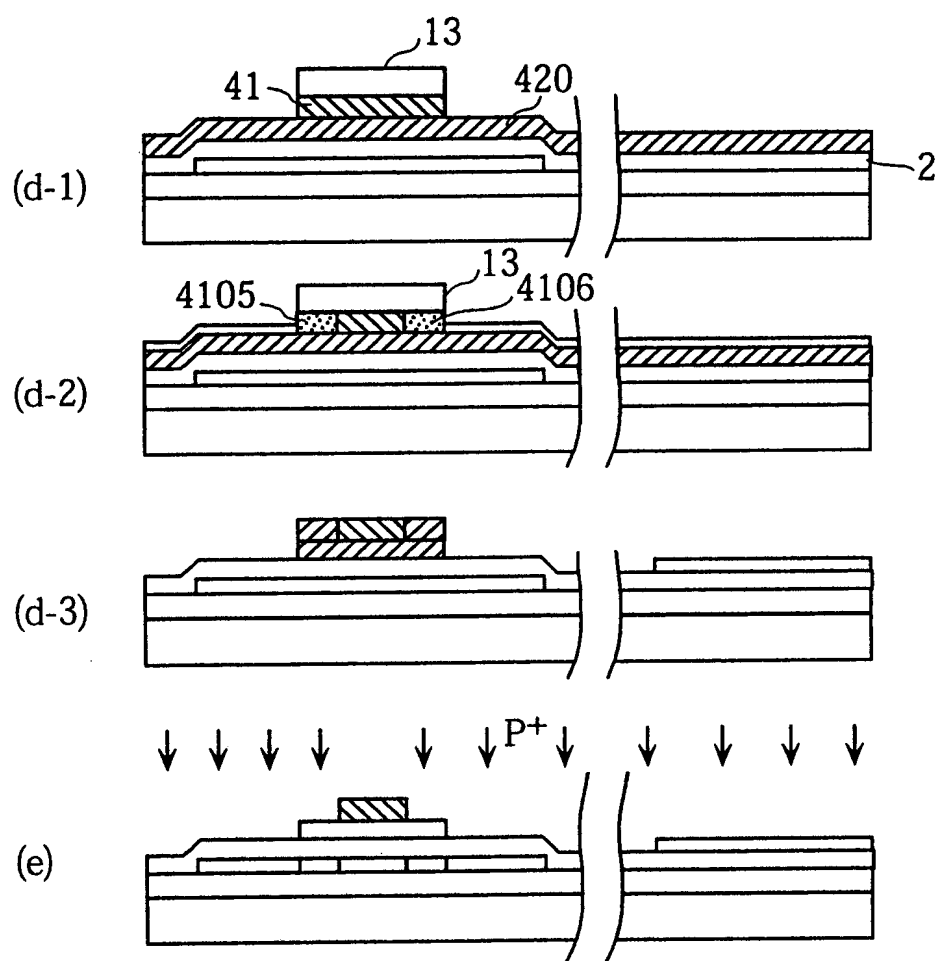


FIG. 28

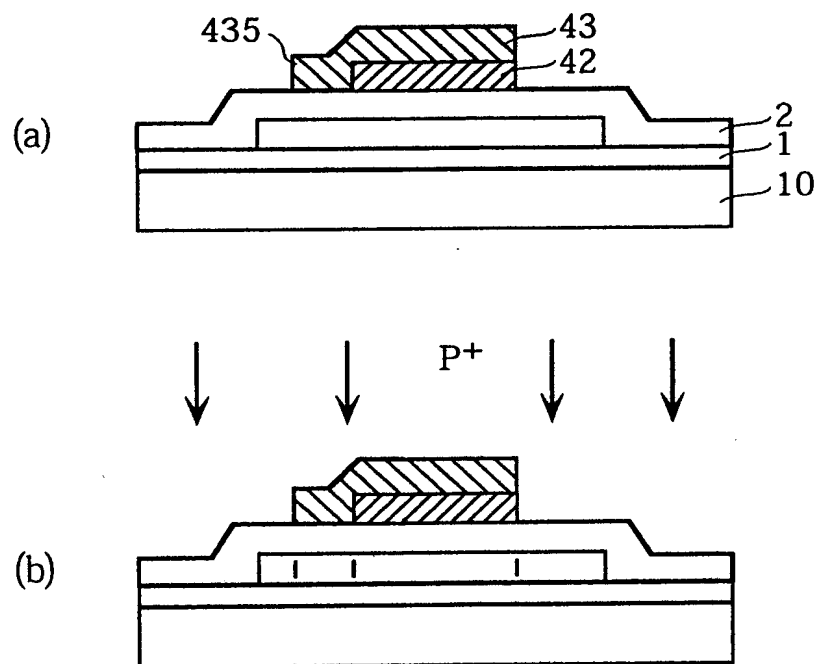


FIG. 29

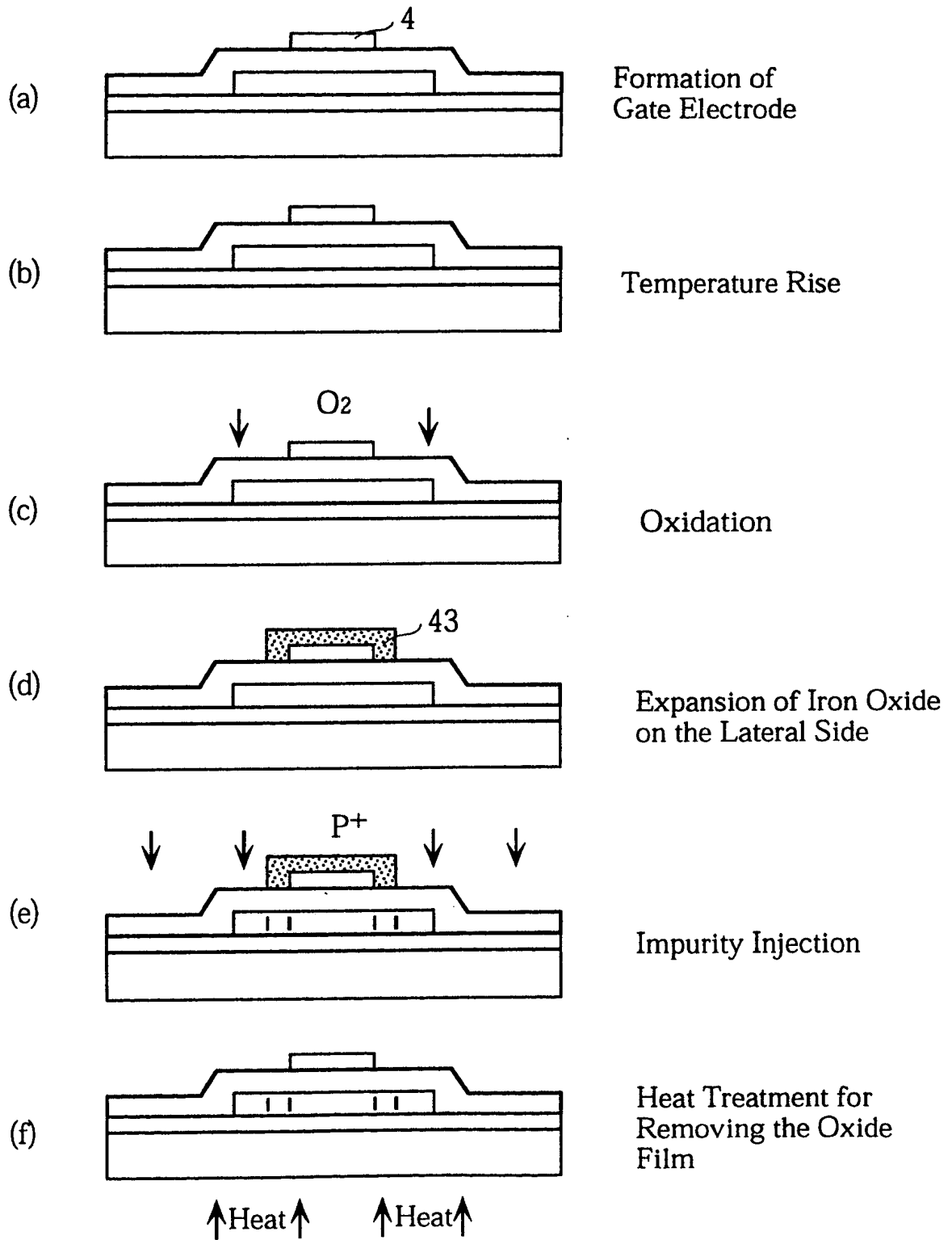


FIG. 30

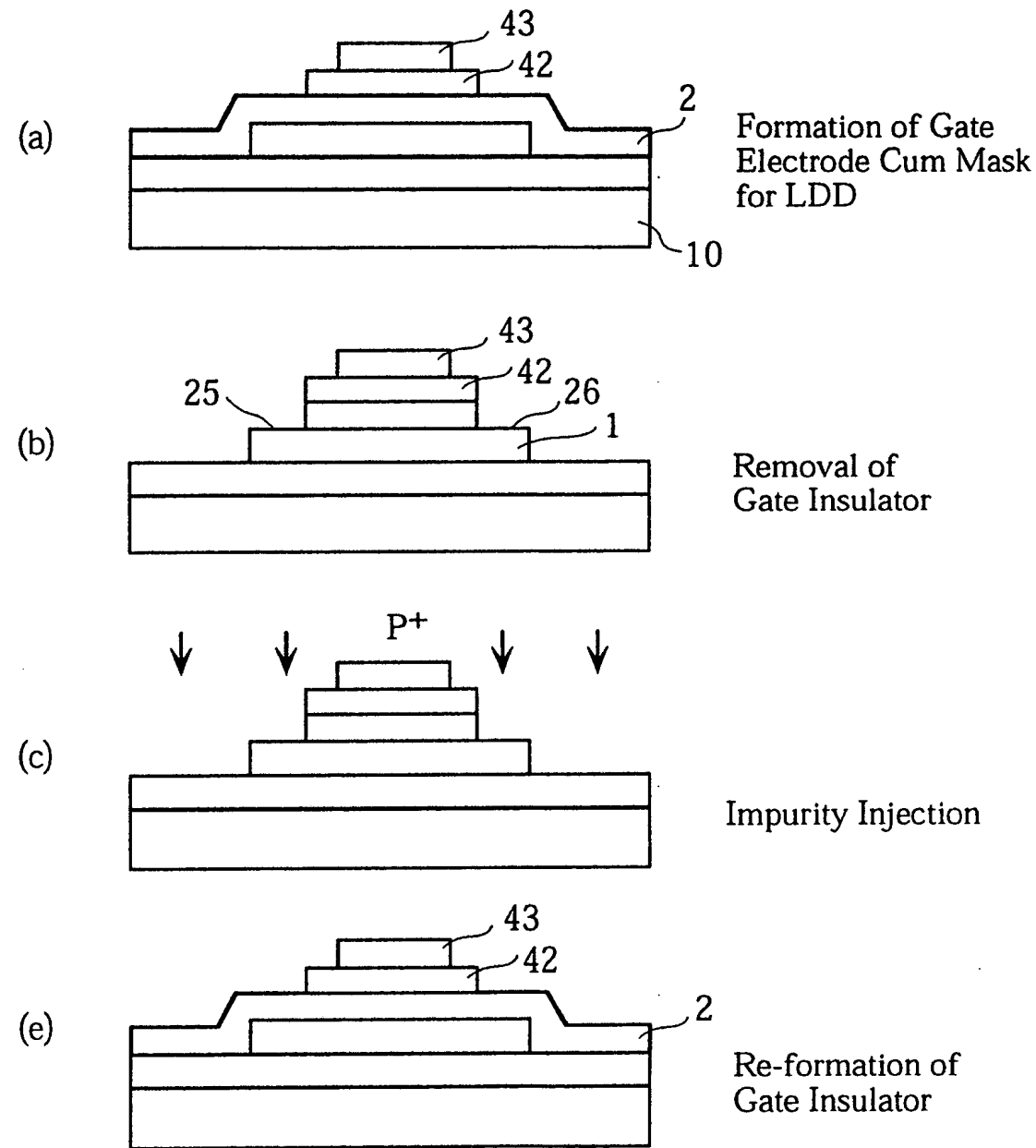


FIG. 31

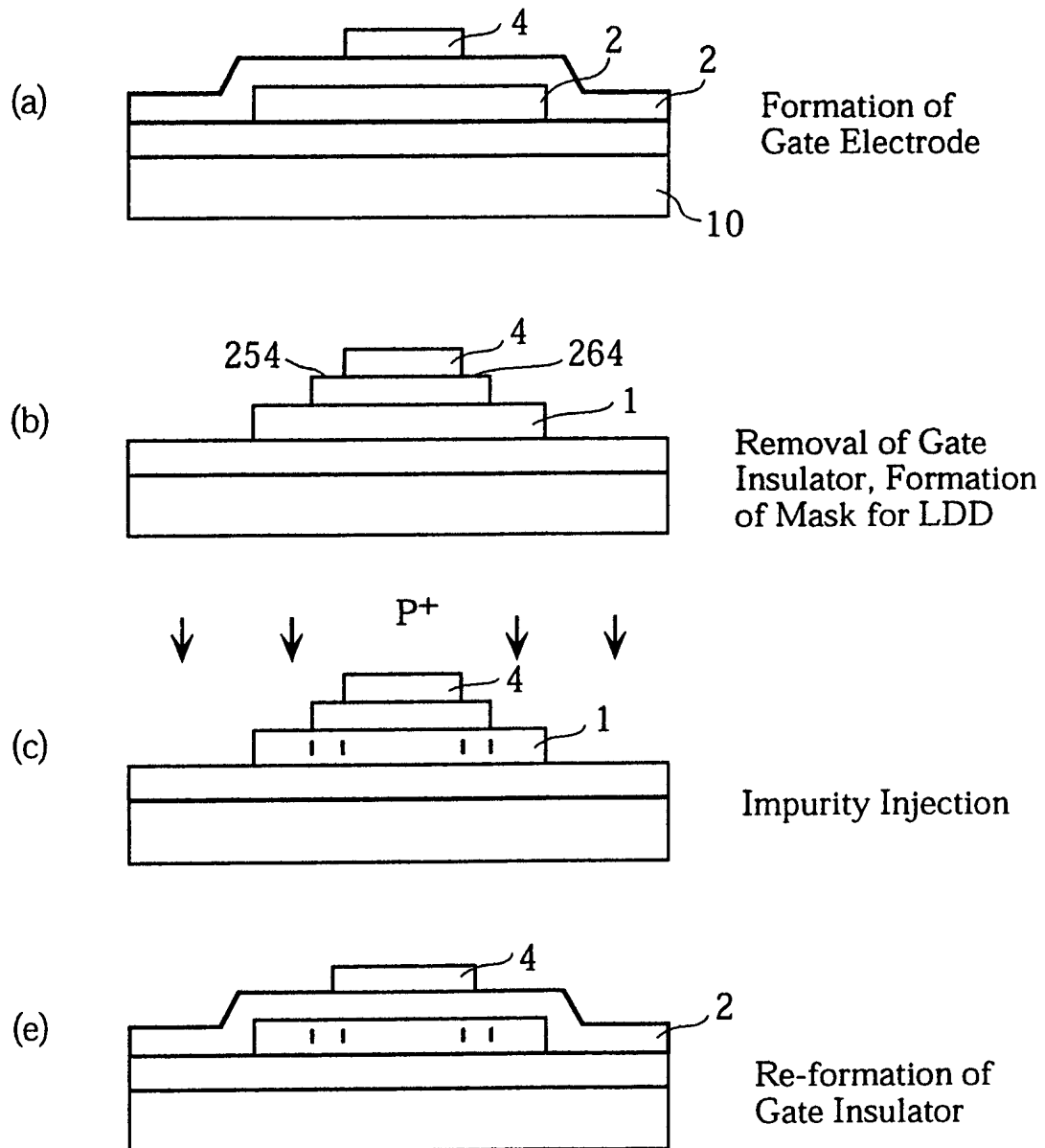
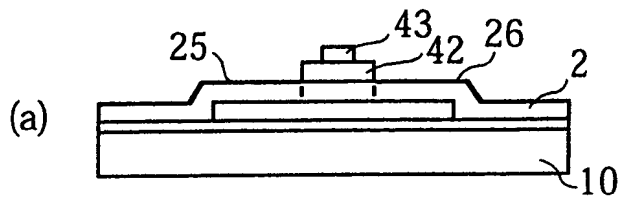
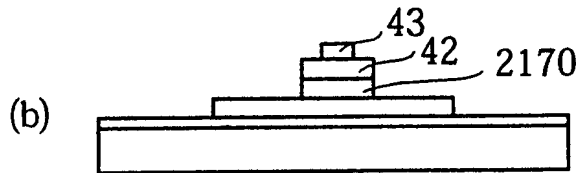


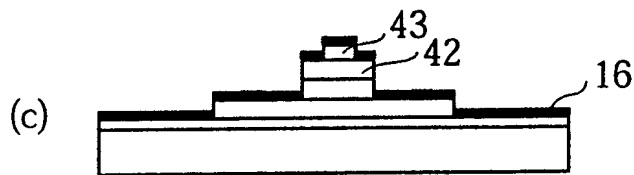
FIG. 32



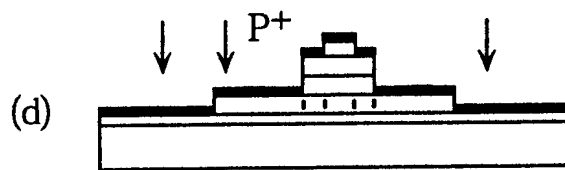
Formation of Gate
Electrode for LDD



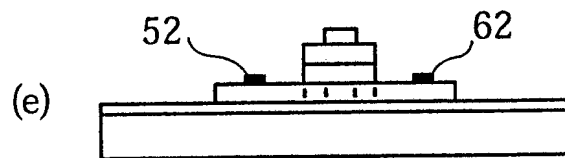
Removal of Gate Insulator



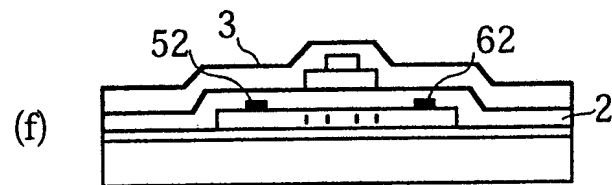
Formation of Ti Film



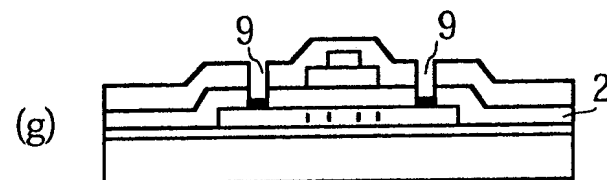
Impurity Injection



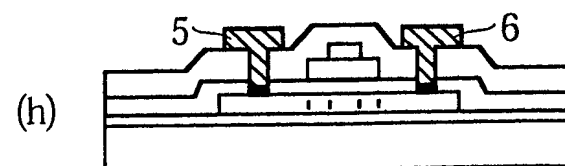
Removal of Ti Film



Re-formation of Gate Insulator,
Formation of Interlayer
Dielectric

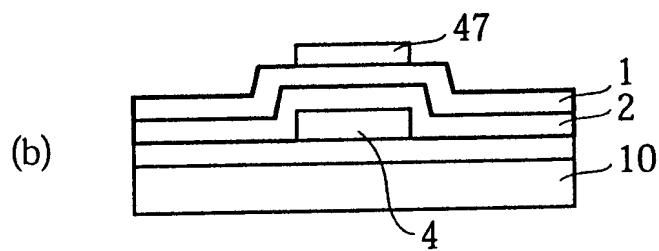
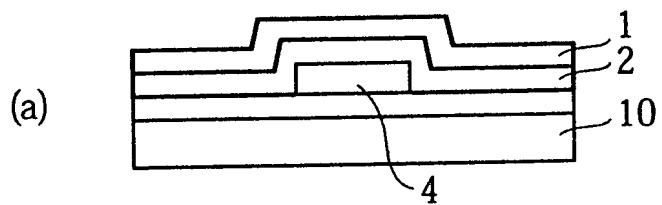


Opening the Contact Hole

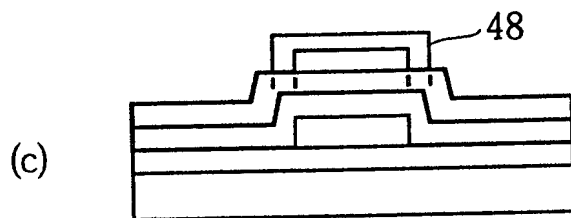


Aluminum Filling

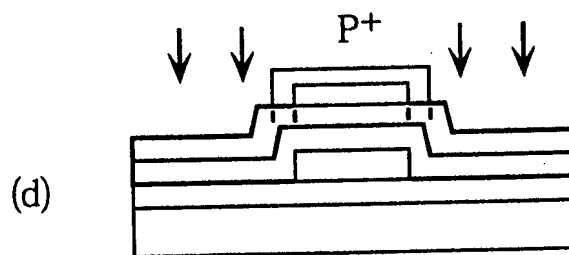
FIG. 33



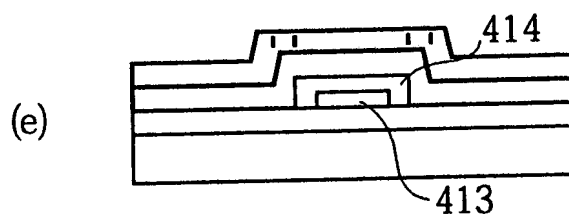
Formation of Lower
Metallic Mask



Formation of Upper
Metallic Mask

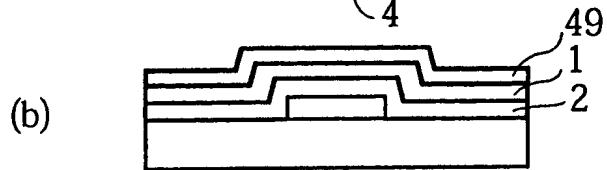
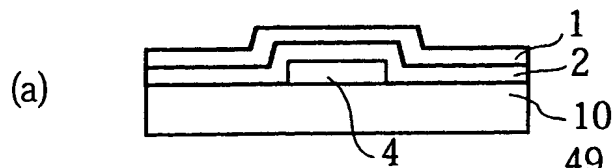


Impurity Injection

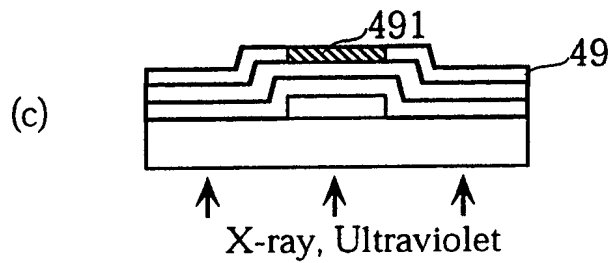


Removal of Mask

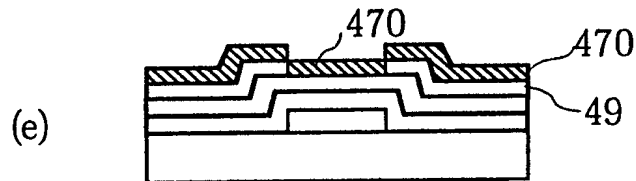
FIG. 34



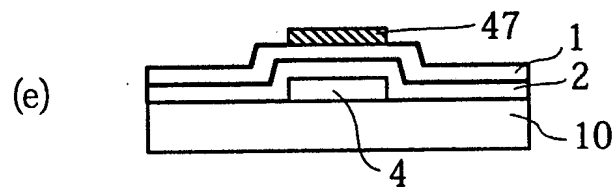
Formation of Photosensitive Resin Film



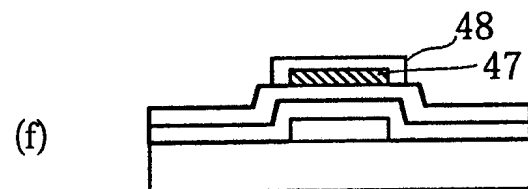
Exposure



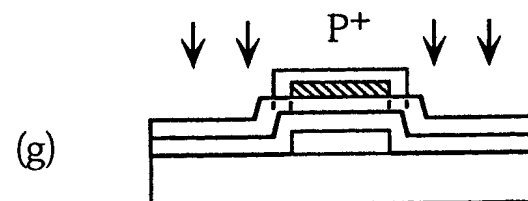
Formation of Lower Metallic Mask



Complete Removal of Resin Film



Formation of Mask



Impurity Injection



Removal of Mask

FIG. 35

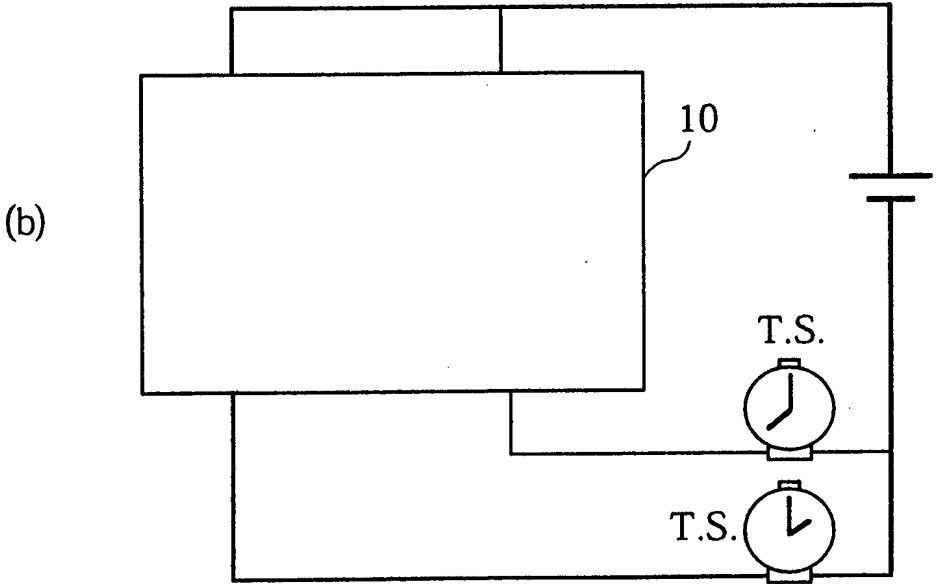
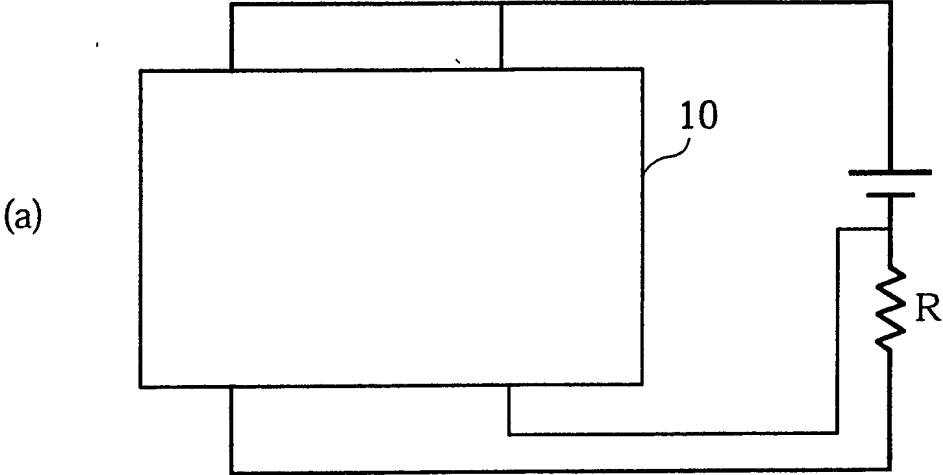


FIG. 36

